


Full Material Declaration for attached parts list

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|  | Diotec Semiconductor AG |
| | DUNS number: 330866844 |
| | -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany |
| | Declarations authorised by: Udo Steinebrunner, Product Manager, - |

Declaration effective from: 15 August 2023 [Approved on 13 March 2026, 11:26 GMT]

Materials and substances

| Use/Location | Material Group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|-------------------|---------------------------|-------------------------------|---|------------|------------------------------------|
| Chip (die) | Other inorganic materials | 0.5% | Silicon | 7440-21-3 | 100% |
| Die attach | Polymeric compounds | 0.19% | OXIRANE, 2,2'-(1,4-BUTANEDIYLBIS(OXYMETHYLENE))BIS- | 2425-79-8 | 4% |
| Encapsulation | EP (Epoxy resin) | 57.81% | Formaldehyde, polymer with (chloromethyl)oxirane and phenol | 9003-36-5 | 16% |
| | | | SILVER, ELEMENTAL | 7440-22-4 | 80% |
| | | | Carbon black | 1333-86-4 | 1% |
| | | | phenolic epoxy resin | 61788-97-4 | 1.5% |
| | | | Silicon Dioxide | 7631-86-9 | 5% |
| | | | Epoxy resin 89 | 26335-32-0 | 8% |
| Inner preparation | Copper alloys | 3.46% | Quartz sand | 60676-86-0 | 84.5% |
| Leadfinish | Tin plating | 1.5% | COPPER, ELEMENTAL | 7440-50-8 | 100% |
| Leadframe | Copper alloys | 36.54% | Tin elemental | 7440-31-5 | 100% |
| | | | IRON, ELEMENTAL | 7439-89-6 | 2.5% |
| | | | COPPER, ELEMENTAL | 7440-50-8 | 97.5% |

Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|-------------------------|------------------------|-----------|---------------|
| SOT-23-5_(IP)_Pb&H-free | Diode / Transistor SMD | 0.014 | g |

